

FEATURES

| Size Design 6.0*6.0*8.0mm

| High Current Handling Capability 10,000A @ 8/20 μs

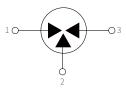
Low Capacitance and Insertion Loss

| Quick Response and Long Service Life

| Moisture sensitivity level: Level 1



6.0*6.0*8.0mm



Schematic Symbol

APPLICATION INFORMATION

| Communication equipment.

Repeaters, Modems

| Telephone Interface,Line cards.

Data communication equipment.

AGENCY APPROVALS

lcon	Solderability	
RoHS	Compliance with 2011/65/EU	
HF	Compliance with IEC61249-2-21:2003	
P	Mean lead free	
R .	UL Certificated E505857	

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated



ELECTRICAL PARAMETER

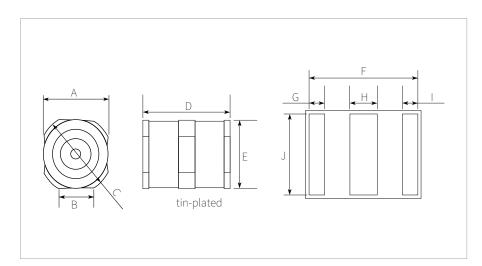
Parameter	Symbol	Rating	Unit
DC Blocking Voltage 1)2)	100V/s	72-108	
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ≤800	V
impuise Spark-over voltage	At 1kV/μs	Typical values of distribution ≤750	V
Impulse Discharge Current 3)	8/20µs	10	KA
Insulation Resistance	DC=50V	≥1	GΩ
Capacitance at 1MHz	V _{DC} =0.5V	≤ 1.5	pF
Weight		~1.25	g
Operating and Storage Temperature		-40~125	°C

¹⁾ At delivery AQL 0.65 level II SO2859 2) In ionized mode

ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards	
High Temperature Storage Test	Temperature: 85°C ; Time:2H	
Low Temperature Storage Test	Temperature: -40°C; Time:2H	
Vibration	Frequency: 10-500Hz; Amplitude: 0.15mm; Time:45min	
Resistance of soldering heat	Temperature: 260°C; Time of dip soldering: 10s,1time	

PRODUCT DIMENSIONS



Ref.	Outline Dimensions	
Kei.	Millimeters	
А	6.0±0.2	
В	3.2	
С	Ф6.8	
D	8.2±0.3	
Е	Ф6.0±0.1	
F	8.8	
G	1.2	
Н	2.2	
	1.2	
J	6	

Outling Dimensions

³⁾ Terms and waveforms in accordance with ITU-T Rec. K. 12; IIEC 61643-311

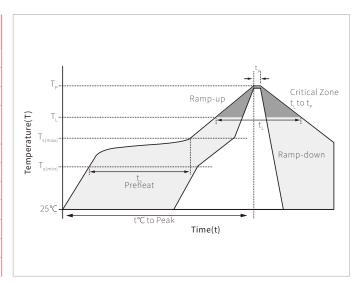


SOLDERABILITY TEST

Solderability		
Solder Pot Temperature	Solder Dwell Time	
245°C ± 5°C	4~6 seconds	

REFLOW PROFILE

Reflow Condition		Lead-free assembly	
	Temperature Min	150°C	
Pre Heat	Temperature Max	200°C	
	Time(min to max)	60~180 secs	
Average ramp up rate (Liquidus)Temp (T _L) to peak		3°C/second max	
T₅(max)to T₋ - Ramp-up Rate			
Reflow	Temperature (T _⊾) (Liquidus)	217°C	
Kellow	$Time(min to max)(t_s)$	60~150 seconds	
PeakTem	perature (T,)	260°C	
Time within 5°C of actual peak Temperature (tp)		20~40 seconds	
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T _P)		8 minutes max.	
Do not exceed		260°C	



ORDERING INFORMATION

Part Number	Size	QTY/Reel	Reel Size
SG3R06B090C	6.0*6.0*8.0mm	600PCS	13 "



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By QR Code





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